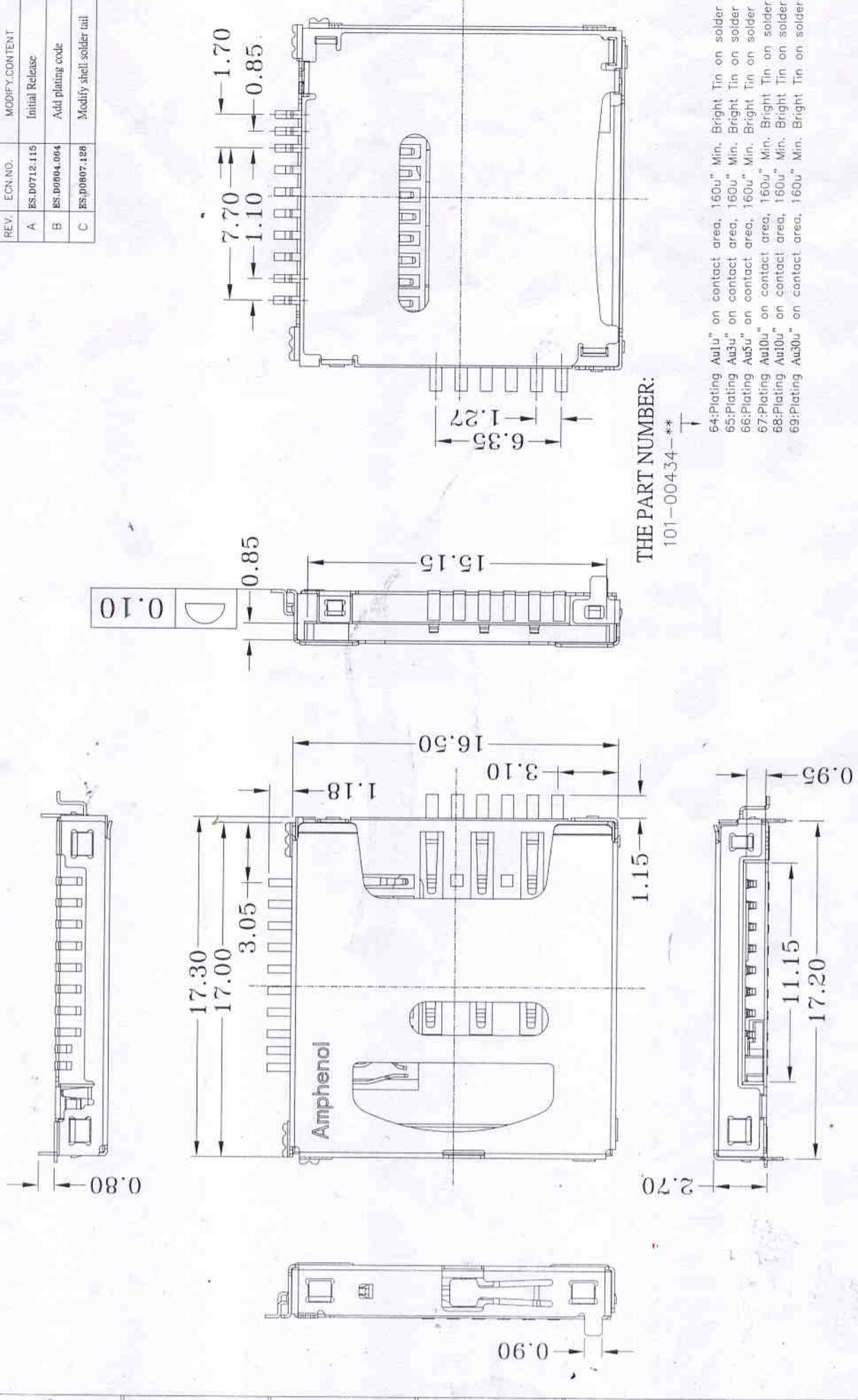


REV.	ECN NO.	MODIFY CONTENT	DATE
A	BS.D0712.115	Initial Release	2007/12/25
B	BS.D0904.064	Add plating code	2008/1/14
C	BS.D0807.129	Modify shell solder tail	2008/07/24

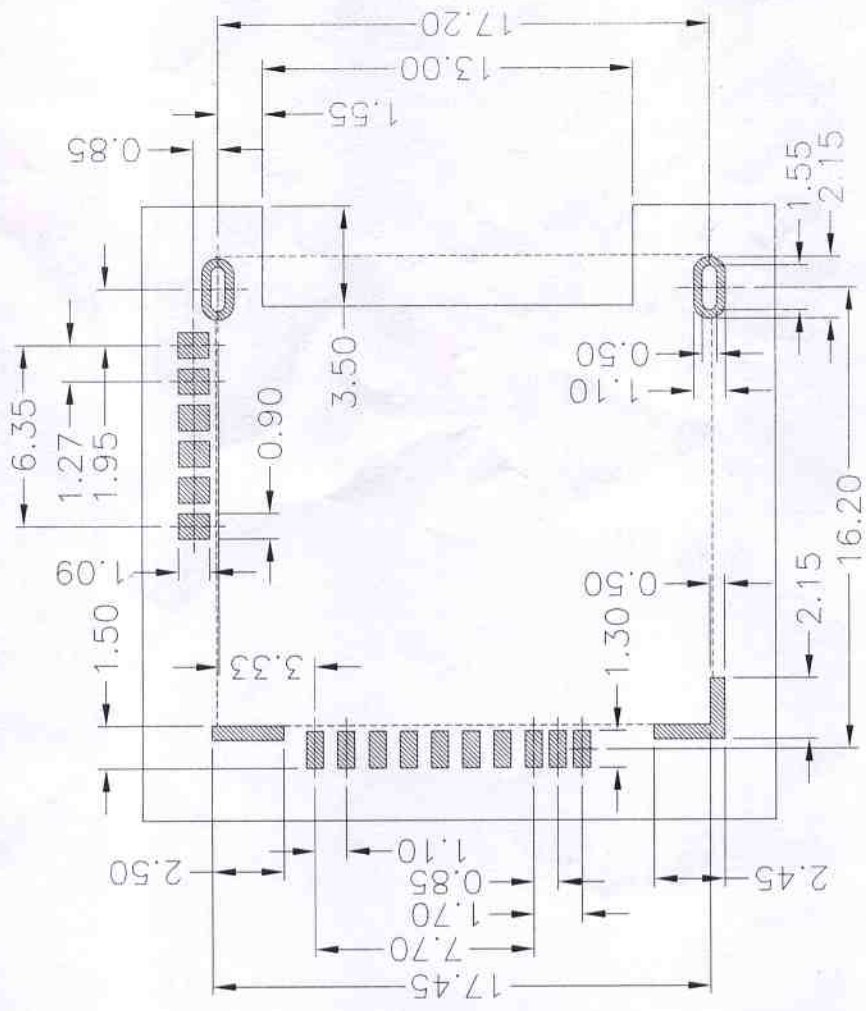
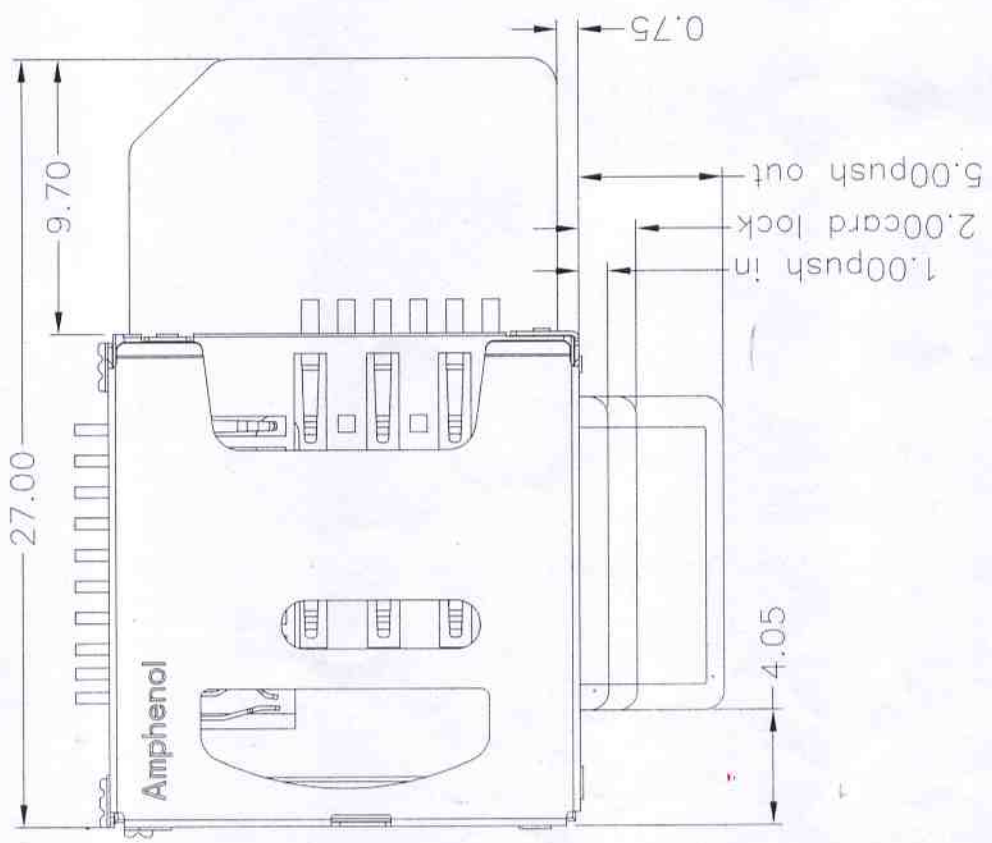


THE PART NUMBER:
101-00434-**-**

- 64:Plating Au10u" on contact area, 160u" Min. Bright Tin on solder tail.
- 65:Plating Au30u" on contact area, 160u" Min. Bright Tin on solder tail.
- 66:Plating Au50u" on contact area, 160u" Min. Bright Tin on solder tail.
- 67:Plating Au10u" on contact area, 160u" Min. Bright Tin on solder tail.
- 68:Plating Au10u" on contact area, 160u" Min. Bright Tin on solder tail.
- 69:Plating Au30u" on contact area, 160u" Min. Bright Tin on solder tail.

GENERAL TOLERANCE		FILE NO.	PART NO.		DRAWN		MATERIAL		SCALE	
X:±0.50	x: ± 5*	10100434	10100434**		Paul		DATE		1:1	
.X±0.38	.x ± 2*	C	SIM+Micro-SD P/P CARD CONN.		CHECKED		2008/07/24		UNITS	
.XX±0.25	.xx ± 1*		1 OF 3		APPROVED		DATE		MM	
Amphenol Shouhmin Industry										

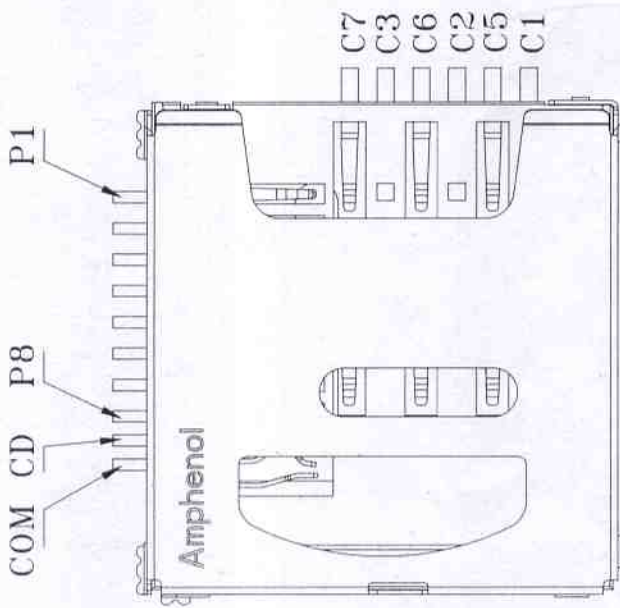
REV.	ECN NO.	MODIFY CONTENT	DATE
A	ES.00712.115	Initial Release	2007/12/25
B	ES.00804.64	Add plating code	2008/1/14
C	ES.00807.128	Modify shell solder tail	2008/07/24



PCB LAYOUT

GENERAL	TOLERANCE	FILE NO.	10100434	PART NO.	10100434**	DRAWN	Paul	MATERIAL	SCALE	1:1
X, ±0.50	X, ± 5°	REV.	C	TITLE	SIM+Micro-SD P/P CARD CONN.	CHECKED		DATE	UNITS	MM
X ±0.58	X ± 2°	SIZE		SHEET	2 OF 3	APPROVED		2008/07/24		
XX ±0.25	.XX ± 1°	A4								
Amphenol Shouhmin Industry										

REV.	ECN-NO.	MODIFY-CONTENT	DATE
A	BS.D0712.115	Initial Release	2007/12/25
B	BS.D0604.064	Add plating code	2008/1/14
C	BS.D0807.128	Modify shell solder tail	2008/07/24



Micro-SD pin assignment	
PIN#	Description
1	Data line[Bit 2]
2	CD/DAT3 ² Card detect/Data line[Bit 2]
3	CMD Command/Response
4	VDD Supply voltage
5	CLK Clock
6	Vss Supply voltage ground
7	DAT0 Data line[Bit 0]
8	DAT1 Data line[Bit 1]

SIM pin assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

NOTE:

- 1.0 Major Dimension: ▼
- 2.0 MECHANICAL CHARACTERISTICS
 - 2.1 Mating cycle: 10000 cycles
- 3.0 ELECTRICAL CHARACTERISTICS
 - 3.1 Current rating : 0.5 A
 - 3.2 Operating voltage : 3.3V
 - 3.3 Contact resistance: 40m ohms max.
 - 3.4 Insulation resistance: 1000M ohms min. at 500 VDC
 - 3.5 Dielectric withstanding voltage:250 VAC/1minute
 - 3.6 Operating Temperature: -0°C~+55°C
 - 3.7 Storage Temperature: -20°C~+65°C
 - 3.8 Operation/Storage humidity: 95% or less
 - 3.9 PRODUCT COMPLIANT TO ROHS DIRECTIVE 2002./95/EC AND ELV 2000./53/EC

GENERAL	TOLERANCE	FILE.NO.	10100434	PART.NO.	10100434**	DRAWN	Paul	MATERIAL	SCALE	1:1	
X.±0.50	x. ± 5 *	REV.	C	TITLE	SIM+Micro-SD P/P CARD CONN.	CHECKED		DATE	2008/07/24	UNITS	MM
X±0.38	.x ± 2 *	SIZE		SHEET	3 OF 3	APPROVED		Amphenol Shouhmin Industry			
.XX±0.25	.xx ± 1 *	A4									

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